

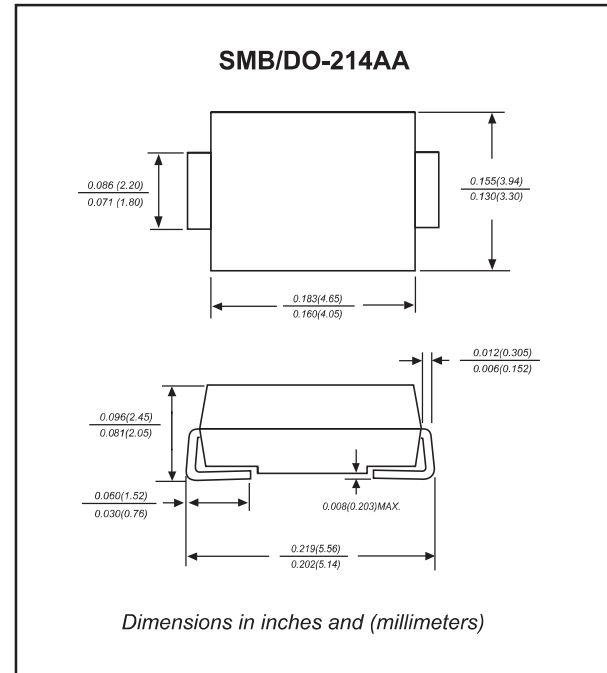
### Features

- Fast switching speed.
- Low profile surface mounted application in order to optimize board space.
- Surface mount package ideally suited for automatic insertion.
- Low power loss, high efficiency.
- High forward surge current capability.
- Glass passivated chip junction.
- Lead-free parts meet RoHS requirements.
- Compliant to Halogen - free

### Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, DO-214AA/SMB
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any

### Package outline



### Maximum ratings and Electrical Characteristics (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.2	$I_O$			1.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC methode)	$I_{FSM}$			30	A
Reverse current	$V_R = V_{RRM} \quad T_J = 25^{\circ}\text{C}$	$I_R$			5.0	$\mu\text{A}$
	$V_R = V_{RRM} \quad T_J = 125^{\circ}\text{C}$				150	
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	$C_J$		20		pF
Storage temperature		$T_{STG}$	-65		+175	$^{\circ}\text{C}$

SYMBOLS	$V_{RRM}^{*1}$ (V)	$V_{RMS}^{*2}$ (V)	$V_R^{*3}$ (V)	$V_F^{*4}$ (V)	$t_{rr}^{*5}$ (ns)	Operating temperature $T_J, (^{\circ}\text{C})$
MURS120-B	200	140	200	0.875	25	
MURS140-B	400	280	400	1.25	50	-55 to +150
MURS160-B	600	420	600			

Note 1. Reverse recovery time test condition,  $I_F=0.5\text{A}$ ,  $I_R=1.0\text{A}$ ,  $I_{RR}=0.25\text{A}$

- \*1 Repetitive peak reverse voltage
- \*2 RMS voltage
- \*3 Continuous reverse voltage
- \*4 Maximum forward voltage@ $I_F=1.0\text{A}$
- \*5 Maximum Reverse recovery time, note 1

### Rating and characteristic curves (MURS120-B THRU MURS160-B)

FIG.1-TYPICAL FORWARD CHARACTERISTICS

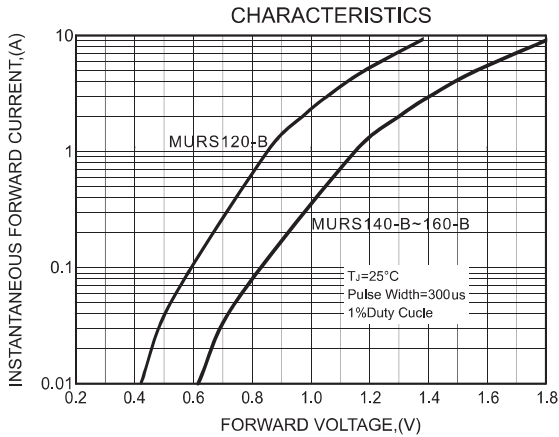


FIG.2-TYPICAL FORWARD DERATING CURVE

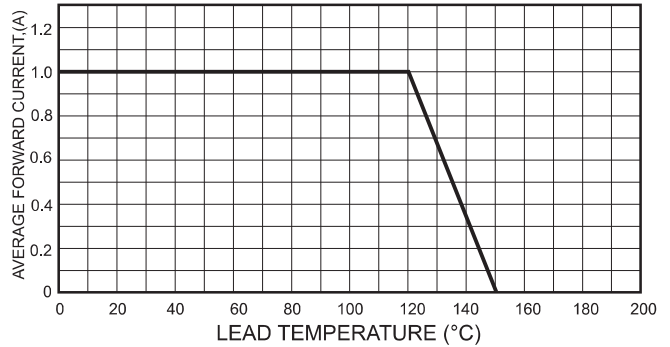


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

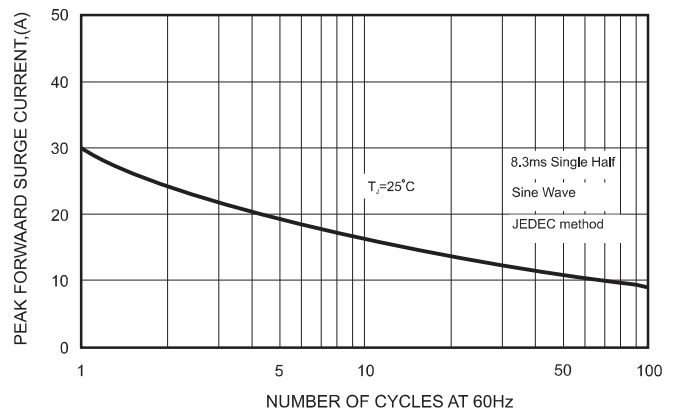
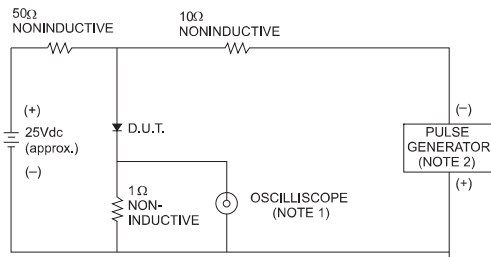


FIG.3- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTICS



NOTES: 1. Rise Time = 7ns max., Input Impedance = 1 megohm, 22pF.  
2. Rise Time = 10ns max., Source Impedance = 50 ohms.

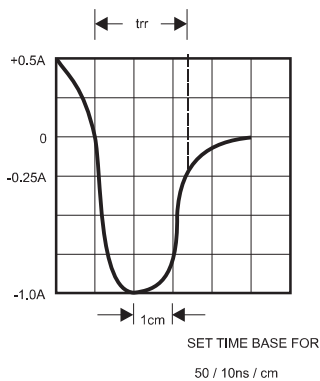
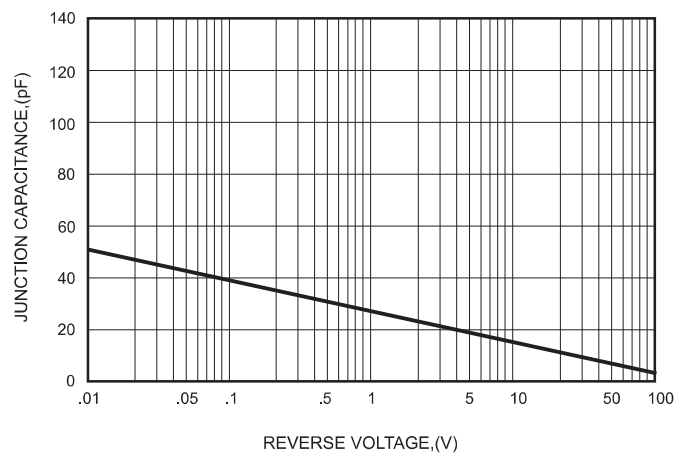




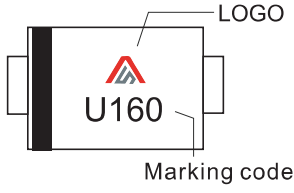
FIG.5-TYPICAL JUNCTION CAPACITANCE



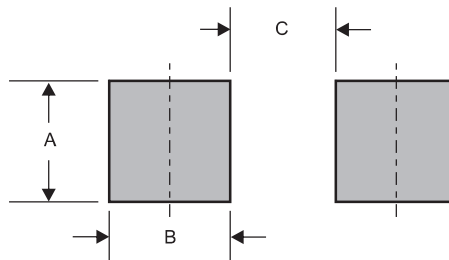
### Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

### Marking

Type number	Marking code	Example
MURS120-B	U120	
MURS140-B	U140	
MURS160-B	U160	

### Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMB	0.090(2.30)	0.098(2.50)	0.070(1.80)